	BLE STAN	DARD										
	VOLTAGE		150V AC CU			ENT			1A			
RATING	OPERATING				CURRENT STORAGE			10-0 TO 00-0 (NOTE 0)			0)	
	TEMPERATUR OPERATING	E RANGE	-35°C TO + 85°C(N	IUIE I)	TEMPER		RE RANGE	= -	-10°C TO + 60°C	•	ა)	
	HUMIDITY RANGE APPLICABLE		40% TO 80% (NOTE 2)		HUMIDITY RANGE APPLAICABLE			40% TO 70% (NOTE				
CONNECTOR		DF13-*S-1. 25C CRI				MP CONTACT DF13-2630SCFA, DF13-					2SCF/	
			SPEC	IFICAT	TION:	S						
IT	ГЕМ		TEST METHOD				RI	EQUI	REMENTS	QT	· AT	
	RUCTION											
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.			AC	ACCORDING TO DRAWING.					X	
MARKING			ED VISUALLY.							X	X	
	IC CHARA				loo) O. I	4.4.7/					
CONTACT RESISTANCE		100m A (DC OR 1000 Hz).			30)mΩ N	IAX.			X	-	
INSULATION		100V DC.			50	Ω MO	MIN.			Х	Τ_	
RESISTANCE VOLTAGE PROOF		500V AC FOR 1 min.			NO	O FLA	SHOVEF	ROR	BREAKDOWN.		-	
										X		
	VICAL CHA			OTIONO	Ta.				TANIOS 00 0 114	. 1		
MECHANICAL OPERATION		50TIMES INSERTIONS AND EXTRACTIONS.				① CONTACT RESISTANCE: 30mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.					-	
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			1~	 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				1 1/	-	
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			19	NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				1 1/	-	
ENVIROI	NMENTAL	CHARA	ACTERISTICS				7.1.(10.					
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 \rightarrow 5 TO 35 \rightarrow 85 \rightarrow 5 TO 35 °C TIME 30 \rightarrow 5 TO 15 \rightarrow 30 \rightarrow 5 TO 15 min UNDER 5 CYCLES.			min ②					N. X	-	
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			2	 CONTACT RESISTANCE: 30mΩ MAX. INSULATION RESISTANCE: 500MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				N. X	_	
RESISTANCE TO		1) FLOW SOLDERING			- 1	NO DEFORMATION OF CASE OF						
SOLDERING HEAT		250±5°CMAX, FOR 3 SECONDS. 2) SOLDERING IRONS:				EXCESSIVE LOOSENESS OF THE TERMINALS.				×	-	
SOLDERABILITY		:290±10°C, FOR 3 SECONDS . SOLDERED AT SOLDER TEMPERATURE.				SOLDER SHALL COVER A MINIMUM OF					-	
		215±5°C	,			95 % OF THE SURFACE BEING IMMERSED. X					-	
NOTE2:NO (NOTE3:APP	CONDENSING LY TO THE CO ORE PCB ON	ONDITION BOARD AI	TURE RISE BY CURRENT. OF LONG TERM STORAGE FTER PCBBOARD, OPERA ED FOR INTERM STORAGE	E FOR UN	PERATU	JRE A	ND			•	•	
		ESCRIPTION	ON OF REVISIONS		DESIGNE	VED			CHECKED		DATE	
	<u> </u>	_										
COUN							APPROV	'ED	TS. SAKATA	08	11. 17	
COUN		cifid , re	fer to JIS C 5402.			}	CHECK	ᄗ	TO VIIMATAWA			
COUN		cifid , re	fer to JIS C 5402.			ļ	CHECKI		TS. KUMAZAWA	08.	11. 14	
COUN		cifid , re	fer to JIS C 5402.			}	DESIGN	ED	SN. KOBAYASHI	08. 08.	11. 14 11. 12	
COUN COUN Unless oth	nerwise spe					-	DESIGN DRAW	ED	SN. KOBAYASHI YK. NAKATSU	08. 08. 08.	11. 14 11. 12 11. 10	
COUN COUN Unless oth	nerwise spe		fer to JIS C 5402. urance Test X:Applicable Te	st	DRA	-	DESIGN	ED	SN. KOBAYASHI	08. 08. 08.	11. 14 11. 12 11. 10	
COUN COUN Unless oth	nerwise spe	t AT:Ass			DRA PART N	WIN	DESIGN DRAW	ED N	SN. KOBAYASHI YK. NAKATSU	08. 08. 08. 20-04	11. 14 11. 12 11. 10	